

Abstract

The present invention is characterized in having a process for forming a pattern by making a substrate having an insulating property, such as a liquid-repellent
5 thin film over a substrate, such as a semiconductor film, selectively have affinity for liquid by plasma generating means 102, and discharging a drop compound to the surface having affinity for liquid by a drop discharging means 103. By putting the region having affinity for liquid, which was selectively formed, between liquid-repellent, a drop after drop landing can be formed without moving the drop
10 landing portion